

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.06647	100.0	1
			<b>Subtotal</b>	<b>0.06647</b>	<b>100</b>	<b>1</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.21373	100.0	3.21545
			<b>Subtotal</b>	<b>0.21373</b>	<b>100</b>	<b>3.21545</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00928	0.03	0.13965
	Copper alloy	Iron (Fe)	7439-89-6	0.03404	0.11	0.51205
	Copper alloy	Copper (Cu)	7440-50-8	30.89852	99.86	464.8483
			<b>Subtotal</b>	<b>30.94184</b>	<b>100</b>	<b>465.5</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.32238	100.0	4.85
			<b>Subtotal</b>	<b>0.32238</b>	<b>100</b>	<b>4.85</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.44789	8.0	81.96
	Filler	Silica fused	60676-86-0	55.15989	81.0	829.845
	Metal hydroxide	Metal hydroxide		0.47669	0.7	7.1715
	Carbon Black	Carbon black	1333-86-4	0.2043	0.3	3.0735
	Polymer	Epoxy resin system		6.80986	10.0	102.45
			<b>Subtotal</b>	<b>68.09863</b>	<b>100</b>	<b>1024.5</b>
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.03569	10.0	0.537
	Silver alloy	Silver (Ag)	7440-22-4	0.00714	2.0	0.1074
	Lead alloy	Lead (Pb)	7439-92-1	0.31411	88.0	4.7256
			<b>Subtotal</b>	<b>0.35694</b>	<b>100</b>	<b>5.37</b>
			<b>Total</b>	<b>99.99999</b>	<b>100</b>	<b>1504.43545</b>

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